LISTING OF CLAIMS:

1-6 (Canceled)

7. (New) A method of transporting a semiconductor dynamic sensor, which includes a semiconductor substrate, a displacement portion formed in the semiconductor substrate in beam structure, the displacement portion being displaceable in response to applied dynamic force, and a plurality of suction portions formed on a surface of the semiconductor substrate in regions separated from the displacement portion, each suction portion being a flat portion having an area larger than a predetermined area, wherein the method comprises:

placing, on the semiconductor substrate, a collet chuck having a plurality of tips having respective suction holes so that the tips contact the suction portions, each hole having an area smaller than the predetermined area of the flat portion;

drawing air through the holes to hold the semiconductor substrate by suction force applied to the suction portion; and

moving the collet chuck with the semiconductor substrate.

8. (New) The method according to claim 7, wherein the suction portions are formed at corners of the semiconductor substrate.

9. (New) The method according to claim 7, wherein the suction portions have no step portion and no wiring pattern to provide the flat portion.

10. (New) A method of transferring a semiconductor dynamic sensor by a collet chuck having a plurality of tips, the method comprising:

forming a plurality of suction portions on a surface of a semiconductor substrate in correspondence with the plurality of tips of the collet chuck, the semiconductor substrate being formed with fixed electrodes and movable electrodes with clearances therebetween, the suction portions being flat and at regions where no electrodes are formed and substantially no air is drawn from the clearances, each of the suction portions having an area larger than a contact area of a corresponding one of the tips;

contacting the tips to the suction portions, respectively; and

drawing air from the suction portions through holes formed in the tips so that the semiconductor substrate is held and transferred by the collet chuck.

11. (New) The method according to claim 10, wherein the number of the suction portions and the number of the tips are equal to each other and all the tips and the suction portions contact each other.